



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-531X309SPC

Test Procedure for a Signal Process card

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	K. Greenwell	8/17/2009
B			
C			

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DATE 8/17/2009	DATE	DATE	DATE 8/17/2009

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1. SCOPE

1.1 This is a functional testing procedure for a Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check Electronic Folder on board for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	H033758	DC-2000

6. TESTING PROCESS

6.1 Setup

6.1.1 Set Jumpers, pots, and dip switches same test board. IC U12 will need to be changed with new prior to testing card, for this chip is not tested in drive.

6.2 Testing Procedure

6.2.1 Using the trend recorder in GE TOOLBOX software view the analog inputs on the PC screen. Verify the table below by changing switch labeled **ANALOG INPUTS** on Control Panel. Tolerances are +/- 5.

NOTE : IF THIS TEST WILL NOT RUN THE SERIAL PORT ON DRIVE IS BAD !!

NOTE: The V $\frac{3}{4}$ VCO column is for the DS200 series cards and their values may vary slightly

SETTING	P1-46	P2-48	P3-50	P4-52	ASP0-51	DVM-49	PF1-8	PF2-10	V3/4VCO
10	71	71	71	71	71	71	71	71	71
20	117	117	117	117	117	12	117	117	117
30	156	156	156	156	156	15	156	156	156
40	194	194	194	194	194	19	194	194	194
50	236	236	236	236	236	23	236	236	236
60	286	286	286	286	286	28	286	286	286
70	351	351	351	351	351	35	351	351	351
80	442	442	442	442	442	44	442	442	442
90	511	511	511	511	511	51	511	511	511

6.3 ***TEST COMPLETE ***

7. NOTES

7.1 None at this time

8. ATTACHMENTS

8.1 None at this time